

**TRADEMARK ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>		NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>		Release and Reassignment	
<b>CONVEYING PARTY DATA</b>			
<b>Name</b>	<b>Formerly</b>	<b>Execution Date</b>	<b>Entity Type</b>
JPMorgan Chase Bank, N.A., as administrative agent		05/25/2011	national association:
<b>RECEIVING PARTY DATA</b>			
<b>Name:</b>	M Cubed Technologies, Inc.		
<b>Street Address:</b>	35 Corporate Drive, Suite 1110		
<b>City:</b>	Trumbull		
<b>State/Country:</b>	CONNECTICUT		
<b>Postal Code:</b>	06468		
<b>Entity Type:</b>	CORPORATION: DELAWARE		
<b>PROPERTY NUMBERS Total: 2</b>			
<b>Property Type</b>	<b>Number</b>	<b>Word Mark</b>	
<b>Registration Number:</b>	2649902		
<b>Registration Number:</b>	2795156	M CUBED TECHNOLOGIES	
<b>CORRESPONDENCE DATA</b>			
<b>Fax Number:</b>	(860)251-5312		
	<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>		
<b>Phone:</b>	860-251-5703		
<b>Email:</b>	trademarks@goodwin.com		
<b>Correspondent Name:</b>	Barb Villandry, Paralegal		
<b>Address Line 1:</b>	Shipman & Goodwin LLP		
<b>Address Line 2:</b>	One Constitution Plaza		
<b>Address Line 4:</b>	Hartford, CONNECTICUT 06103-1919		
<b>ATTORNEY DOCKET NUMBER:</b>	42924-24		
<b>NAME OF SUBMITTER:</b>	Barb Villandry, Paralegal		
<b>Signature:</b>	/Barb Villandry/		

OP \$65.00 2649902

Date:

05/26/2011

Total Attachments: 2

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**RELEASE AND REASSIGNMENT**

This **RELEASE AND REASSIGNMENT** is made this 25<sup>th</sup> day of May, 2011 by JPMORGAN CHASE BANK, N.A., as administrative agent.

**WITNESSETH:**

**WHEREAS**, JPMorgan Chase Bank, N.A. with an office at 2 Corporate Drive, Suite 730, Shelton, Connecticut 06484, as administrative agent for the ratable benefit of JPMorgan Chase Bank, N.A. ("**JPM**"), and other lenders (collectively, the "**Assignor**") and M Cubed Technologies, Inc., a Delaware corporation having a mailing address at 35 Corporate Drive, Suite 1110, Trumbull, Connecticut 06468 ( the "**Assignee**"), are parties to a certain Security Agreement, dated as of April 8, 2005 (the "Security Agreement"), pursuant to which Assignee granted a security interest in and to the Collateral (including without limitation all of the Assignee's patents, patent applications, trademarks, service marks, trademark and service mark registrations, and trademark and service mark applications listed on Schedule A attached hereto).

**WHEREAS**, Assignee has requested that JPM release its security interest in the Collateral and reassign the same to Assignee.

**NOW THEREFORE**, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged:

1. JPM hereby releases its security interest and terminates all of its right, title and interest in all of the Collateral arising pursuant to the Security Agreement, including without limitation, the patents, patent applications, trademarks, service marks, and trademark and service mark registrations and applications listed on Schedule A, attached hereto and made a part hereof, and (a) renewals and extensions thereof, (b) all income, royalties, damages and payments now and hereafter due and/or payable under and with respect thereto, including without limitation, damages and payments for past or future infringement thereof, (c) the right to sue for past, present and future infringements thereof, and (d) all rights corresponding thereto throughout the world; and the goodwill of Assignee's business connected with and symbolized by the trademarks and service marks.

2. JPM hereby reassigns, grants and conveys to Assignee, without any representation, recourse or undertaking by JPM, all of JPM's right, title and interest in and to the Collateral.

**IN WITNESS WHEREOF**, JPM has caused this Release and Reassignment to be duly executed by its duly authorized officer as of the day and year first above written.

**JPMORGAN CHASE BANK, N.A.**

By: 


Authorized Officer

## SCHEDULE A

### PATENTS

No.	Patent	App./Reg. No.
1	Low expansion metal matrix composites	6,355,340
2	[Improved] Silicon carbide composites and methods for making same	6,503,572
3	Silicon carbide armor bodies, and methods for making same	6,609,452
4	Silicon carbide armor bodies, and methods for making same	6,805,034
5	Composite adhesive	6,841,615
6	Boron carbide composite bodies, and methods for making same	6,862,970
7	Methods for making composite bonded structures	6,863,759
8	Method for brazing ceramic-containing bodies, and articles made thereby	6,884,511
9	Toughness enhanced silicon-containing composite bodies, and methods for making same	6,995,103
10	Ceramic-rich composite armor, and methods for making same	7,104,177
11	Low CTE metal-ceramic composite articles, and methods for making same	7,244,034
12	Method for brazing ceramic-containing bodies, and articles made thereby	7,270,885
13	Boron carbide composite bodies, and methods for making same	7,332,221

### TRADEMARKS

No.	Mark	App./Reg. No.
1		2,649,902
2	M CUBED TECHNOLOGIES	2,795,156